

CryptoMemory and Secure Memory: Standard Product Offerings

The family of CryptoMemory® devices in the following tables are available as standard products. Options are listed for each device including, Smart Card Modules, Standard Packages and Wafers. Ordering codes indicate specific options to be used with the device number (e.g., AT88SC1616C-MJ denotes the 16K CryptoMemory in a “J” module). Options marked with an “m” are available, and those marked with a “1” are most commonly sold and therefore may have reduced leadtimes. Actual ship quantity in module form will vary +/- 20% depending upon die per wafer.

The following pages give details of the package options for the various ordering codes.

0.0.1 CryptoMemory

Devices	Smart Card Modules (Commercial Temperature)		Standard Packages (Industrial Temperature)		7 mil Wafer (Industrial Temperature)
	-MJ	-MP	-SU	-PU	-WI
AT88SC0104C	1	m	1	m	m
AT88SC0204C	1	m	1	m	m
AT88SC0404C	1	m	1	m	m
AT88SC0808C	1	m	1	m	m
AT88SC1616C	1	m	1	m	m
AT88SC3216C	1		1	m	m
AT88SC6416C	1		1	m	m
AT88SC12816C	1		1	m	m
AT88SC25616C	1		1	m	m



CryptoMemory and Secure Memory

Standard Product Offering



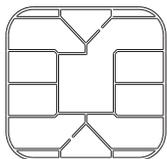
0.0.2 Secure Memory

Devices	Smart Card Modules (Commercial Temperature)		Standard Packages (Industrial Temperature)		7 mil Wafer (Industrial Temperature)
	-09ET-00	-09PT-00	-10SU-00	-10PU-00	-10WI-00
AT88SC102	1	m			m
AT88SC1003	1	m			m
AT88SC153	1	m	1	m	m
AT88SC1608	1	m	1	m	m

- Notes:
1. m = available
 2. 1 = most commonly sold and may have reduced leadtimes
 3. All devices operate at 2.7–5.5V except AT88SC1003, which operates at 4.5–5.5V.
 4. All modules and packages are RoHS compliant.

CryptoMemory Ordering Codes Smart Card Modules

Ordering Code: AT88SCxxxxC-MJ

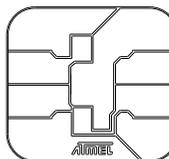


Module Size: M2
Dimension*: 12.6 x 11.4 [mm]
Glob Top: Round - 08.0 [mm]
Thickness: 0.58 [mm]
Pitch: 14.25 mm

Products:

AT88SC0104C
AT88SC0204C
AT88SC0404C
AT88SC0808C
AT88SC1616C
AT88SC3216C
AT88SC6416C
AT88SC12816C
AT88SC25616C

Ordering Code: AT88SCxxxxC-MP



Module Size: M2
Dimension*: 12.6 x 11.4 [mm]
Glob Top: Square – 8.8 x 8.8 [mm]
Thickness: 0.58 [mm]
Pitch: 14.25 mm

Products:

AT88SC0104C
AT88SC0204C
AT88SC0404C
AT88SC0808C
AT88SC1616C

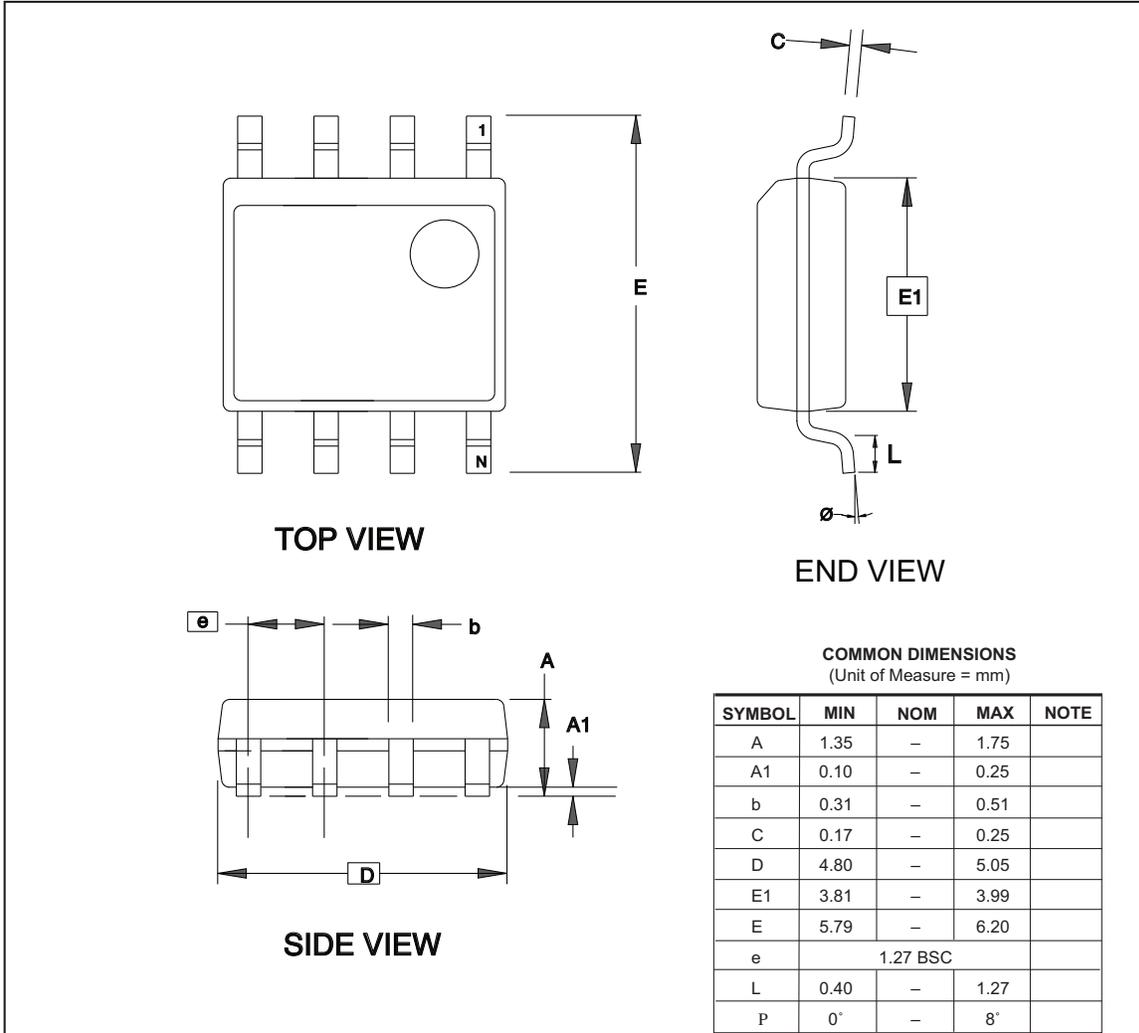
Note: *The module dimensions listed refer to the dimensions of the exposed metal contact area.
The actual dimensions of the module after excise or punching from the carrier tape are typically 0.4 mm greater in both directions (i.e., a punched M2 module will yield 13.0 x 11.8 mm)

CryptoMemory Ordering Codes Standard Packages

Ordering Code: AT88SCxxxxC-SU

8S1, 8-lead, 0.150" Wide, Plastic Gull Wing Small Outline (JEDEC SOIC)

Products: AT88SC0104C, AT88SC0204C, AT88SC0404C, AT88SC0808C,
AT88SC1616C, AT88SC3216C, AT88SC6416C, AT88SC12816C,
AT88SC25616C



Note: These drawings are for general information only. Refer to JEDEC Drawing MS-012, Variation AA for proper dimensions, tolerances, datums, etc.

3/17/05



1150 E. Cheyenne Mtn. Blvd.
Colorado Springs, CO 80906

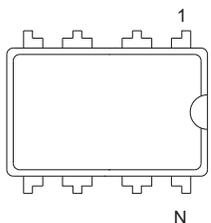
TITLE
8S1, 8-lead (0.150" Wide Body), Plastic Gull Wing
Small Outline (JEDEC SOIC)

DRAWING NO.	REV.
8S1	C

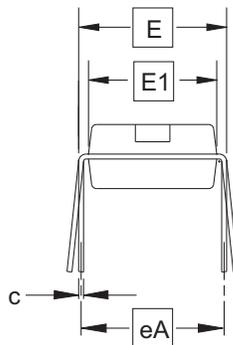
CryptoMemory Ordering Codes Standard Packages

Ordering Code: AT88SCxxxxC-PU

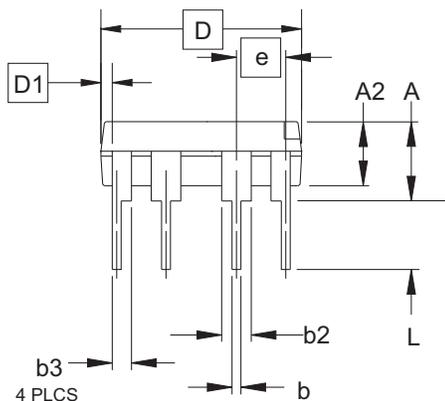
8P3, 8-lead, 0.300" Wide, Plastic Dual In-line Package (PDIP)
 Products: AT88SC0104C, AT88SC0204C, AT88SC0404C, AT88SC0808C,
 AT88SC1616C, AT88SC3216C, AT88SC6416C, AT88SC12816C,
 AT88SC25616C



Top View



End View



Side View

COMMON DIMENSIONS (Unit of Measure = inches)

SYMBOL	MIN	NOM	MAX	NOTE
A			0.210	2
A2	0.115	0.130	0.195	
b	0.014	0.018	0.022	5
b2	0.045	0.060	0.070	6
b3	0.030	0.039	0.045	6
c	0.008	0.010	0.014	
D	0.355	0.365	0.400	3
D1	0.005			3
E	0.300	0.310	0.325	4
E1	0.240	0.250	0.280	3
e	0.100 BSC			
eA	0.300 BSC			4
L	0.115	0.130	0.150	2

- Notes:
1. This drawing is for general information only; refer to JEDEC Drawing MS-001, Variation BA for additional information.
 2. Dimensions A and L are measured with the package seated in JEDEC seating plane Gauge GS-3.
 3. D, D1 and E1 dimensions do not include mold Flash or protrusions. Mold Flash or protrusions shall not exceed 0.010 inch.
 4. E and eA measured with the leads constrained to be perpendicular to datum.
 5. Pointed or rounded lead tips are preferred to ease insertion.
 6. b2 and b3 maximum dimensions do not include Dambar protrusions. Dambar protrusions shall not exceed 0.010 (0.25 mm).

01/09/02



2325 Orchard Parkway
 San Jose, CA 95131

TITLE
 8P3, 8-lead, 0.300" Wide Body, Plastic Dual
 In-line Package (PDIP)

DRAWING NO.
 8P3

REV.
 B

Note: Dimensions in inches and (millimeters).



Secure Memory Ordering Codes Smart Card Modules

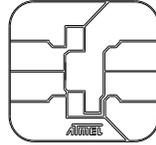
Ordering Code: AT88SCxxx-09ET-00



Module Size: M2
 Dimension*: 12.6 x 11.4 [mm]
 Glob Top: Round – ? 8.0 [mm]
 Thickness: 0.58 [mm]
 Pitch: 14.25 mm

Products:
 AT88SC102
 AT88SC1003
 AT88SC153
 AT88SC1608

Ordering Code: AT88SCxxx-09PT-00



Module Size: M2
 Dimension*: 12.6 x 11.4 [mm]
 Glob Top: Square – 8.8 x 8.8 [mm]
 Thickness: 0.58 [mm]
 Pitch: 14.25 mm

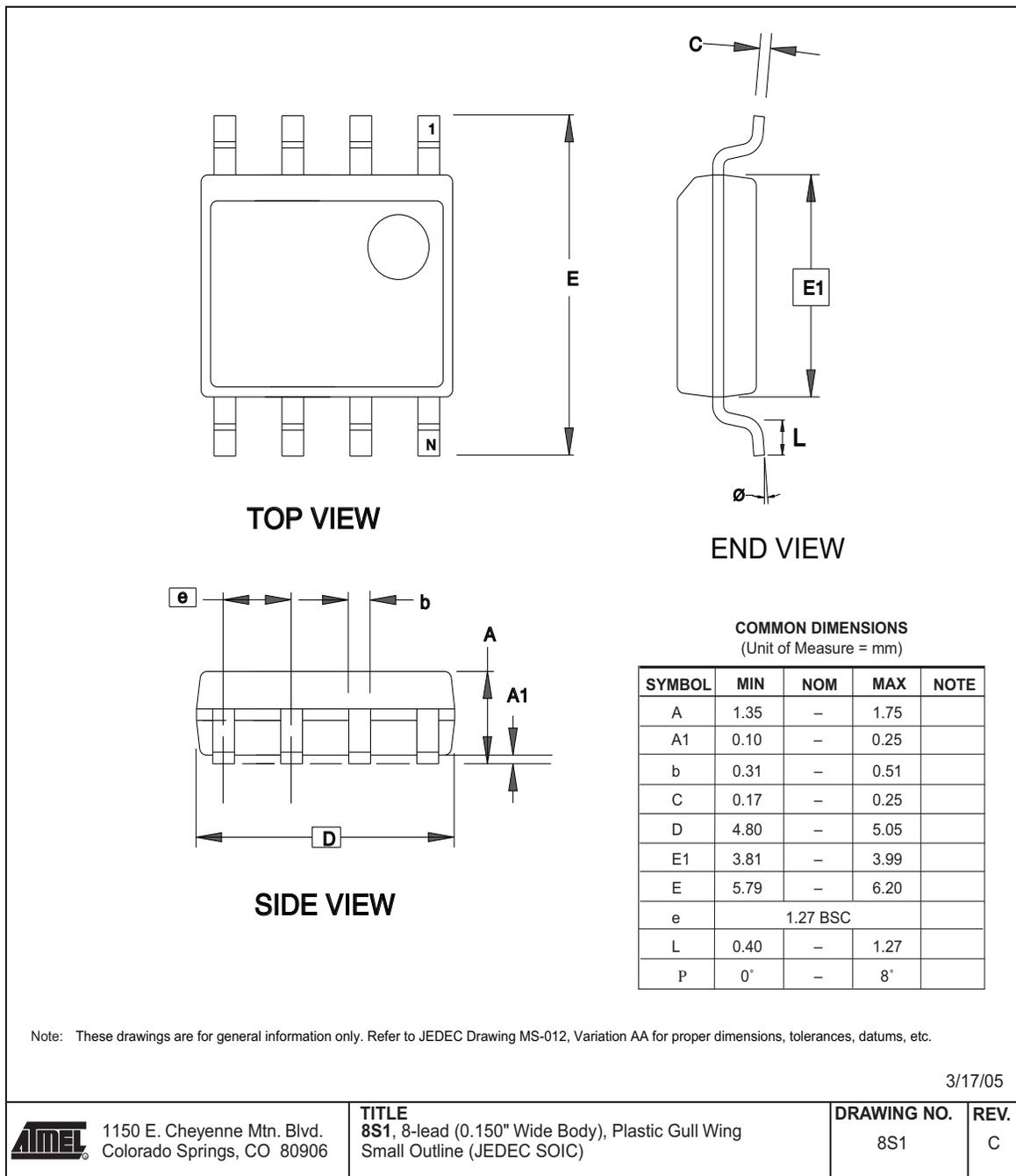
Products:
 AT88SC102
 AT88SC1003
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Note: *The module dimensions listed refer to the dimensions of the exposed metal contact area.
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 (i.e., a punched M2 module will yield 13.0 x 11.8 mm)

Secure Memory Ordering Codes Standard Packages

Ordering Code: AT88SCxxx-10SU-00

8S1, 8-lead, 0.150" Wide, Plastic Gull Wing Small Outline (JEDEC SOIC)
Products: AT88SC153, AT88SC1608

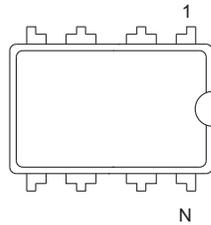


Secure Memory Ordering Codes Standard Packages

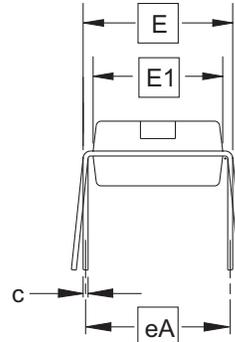
Ordering Code: AT88SCxxx-10PU-00

8P3, 8-lead, 0.300" Wide, Plastic Dual Inline Package (PDIP)

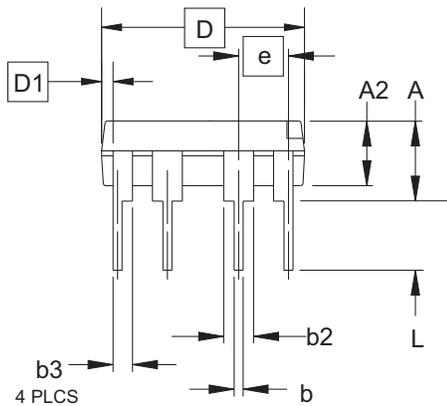
Products: AT88SC153, AT88SC1608



Top View



End View



Side View

COMMON DIMENSIONS

(Unit of Measure = inches)

SYMBOL	MIN	NOM	MAX	NOTE
A			0.210	2
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b	0.014	0.018	0.022	5
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D	0.355	0.365	0.400	3
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eA	0.300 BSC			4
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01/09/02



2325 Orchard Parkway
San Jose, CA 95131

TITLE

8P3, 8-lead, 0.300" Wide Body, Plastic Dual
In-line Package (PDIP)

DRAWING NO.

8P3

REV.

B

Note: Dimensions in inches and (millimeters).

1. Revision History

Date	Doc. Rev.	Comments
6/2008	5044F	Updated to new template
7/2006	5044E	Revision history implemented. Added new Smart Card module and plastic package offerings, including RoHS packages.



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